

SST-50 W LEDs

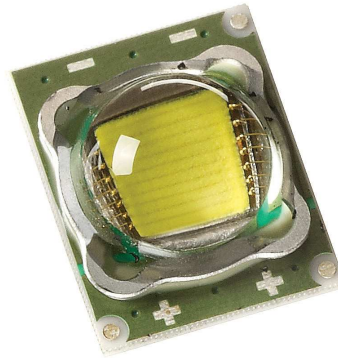


Table of Contents

Technology Overview	2
Test Specifications	2
White Binning Structure	3
Chromaticity Bins	4
Product Shipping & Labeling Information	7
Electrical Characteristics	8
Lifetime & Lumen Maintenance	9
Spectral Characteristics	9
Radiation Patterns	10
Thermal Resistance	10
Mechanical Dimensions	11
Solder Profile	13
Tape & Reel Drawing	14
Ordering Information	15

Features:

- Extremely high optical output: Over 1,150 lumens from a single chip (white)
- Extremely high efficiency: Over 100 lumens per watt at 1.75A
- High thermal conductivity package - junction to case thermal resistance of only 2.45 °C/W
- Large, monolithic chip with uniform emitting area of 5 mm²
- Lumen maintenance of greater than 70% after 60,000 hours
- Environmentally friendly: RoHS compliant
- Variable drive currents: less than 1 A through 5 A
- High reliability
- Electrically isolated thermal path

Applications

- Replacement Lamps
- High Bay Lighting
- Street Lighting
- Consumer Portable
- Architectural Lighting
- Retail Lighting
- Residential Lighting
- Spot Lighting

Technology Overview

Luminus Big Chip LEDs™ benefit from a suite of innovations in the fields of chip technology, packaging and thermal management. These breakthroughs allow illumination engineers and designers to achieve solutions that are high brightness and high efficiency.

Luminus Technology

Luminus' technology enables large area LED chips with uniform brightness over the entire LED chip surface. The optical power and brightness produced by these large monolithic chips enable solutions which replace arc and halogen lamps where arrays of traditional high power LEDs cannot.

Packaging Technology

Thermal management is critical in high power LED applications. With a thermal resistance from junction to case of 2.45° C/W. Luminus SST-50 LEDs have the lowest thermal resistance of any LED on the market. This allows the LED to be driven at higher current densities while maintaining a low junction temperature, thereby resulting in brighter solutions and longer lifetimes.

Reliability

Designed from the ground up, Luminus Big Chip LEDs are one of the most reliable light sources in the world today. Big Chip LEDs have passed a rigorous suite of environmental and mechanical stress tests, including mechanical shock, vibration, temperature cycling and humidity, and have been fully qualified for use in extreme high power and high current applications. With very low failure rates and median lifetimes that typically exceed 60,000 hours, Luminus Big Chip LEDs are ready for even the most demanding applications.

Environmental Benefits

Luminus LEDs help reduce power consumption and the amount of hazardous waste entering the environment. All Big Chip LED products manufactured by Luminus are RoHS compliant and free of hazardous materials, including lead and mercury.

Understanding Big Chip LED Test Specifications

Every Luminus LED is fully tested to ensure that it meets the high quality standards expected from Luminus' products.

Testing Temperature

Luminus surface mount LEDs are typically tested with a 20 msec input pulse and a junction temperature of 25°C. Expected flux values in real world operation can be extrapolated based on the information contained within this product data sheet.

Multiple Operating Points

The tables on the following pages provide typical optical and electrical characteristics. Since the LEDs can be operated over a wide range of drive conditions (currents from less than 1.0 A to 5.0 A, and duty cycle from <1% to 100%), multiple drive conditions are possible.

SST-50 LEDs are production tested at 1.75 A.

SST-50 White Binning Structure

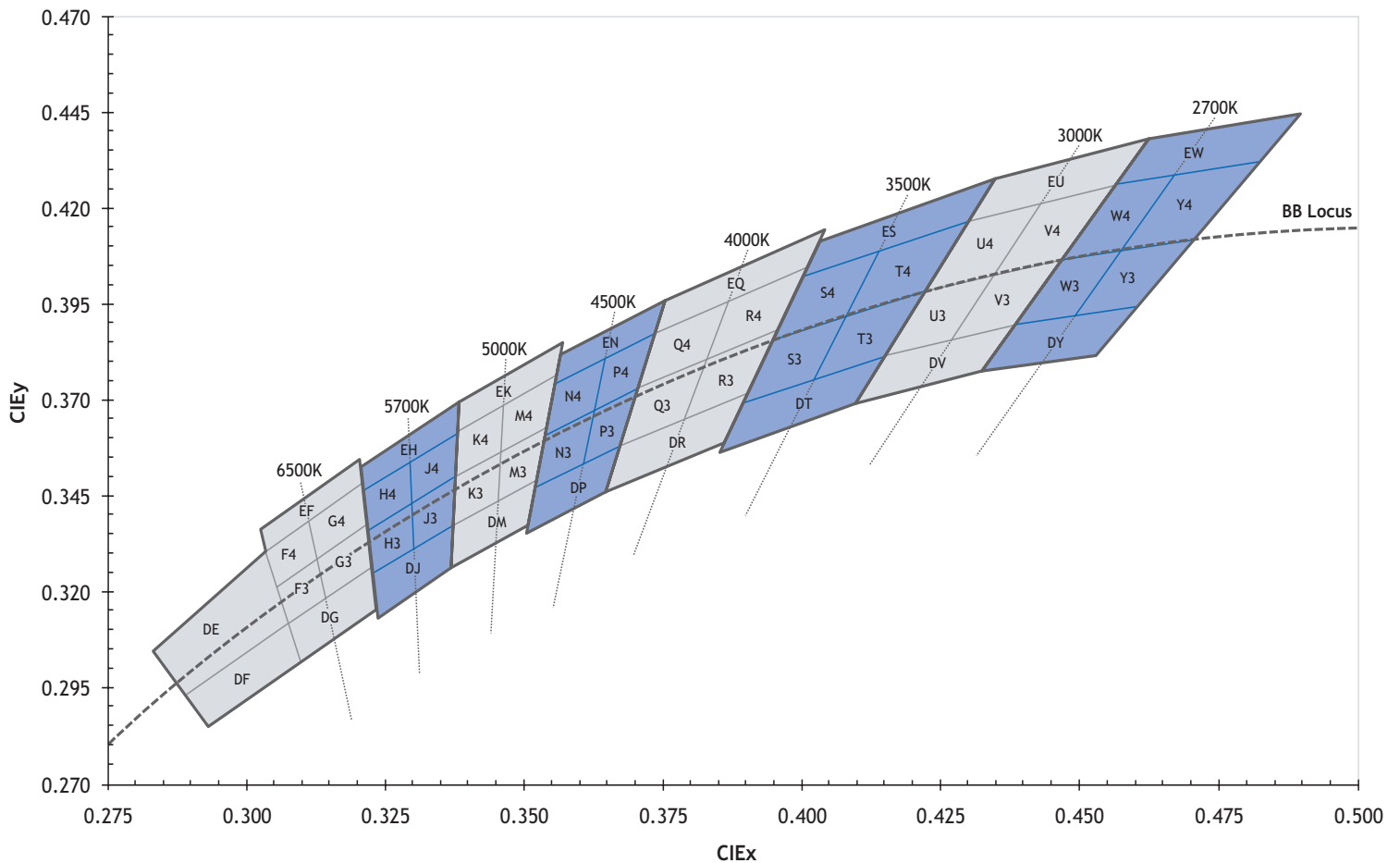
SST-50 LEDs are tested for luminous flux and chromaticity at a drive current of 1.75 A (350 mA/mm²) and placed into one of the following luminous flux (FF) and chromaticity (WW) bins:

Flux Bin (FF)	Minumum Flux (lm) @ 1.75A	Maximum Flux (lm) @ 1.75A
G2	300	325
G3	325	350
H	350	375
H2	375	400
H3	400	425
J	425	450
J2	450	475
J3	475	500
K	500	530

*Note: Luminus maintains a +/- 6% tolerance on flux measurements.

Chromaticity Bins

Luminus' Standard Chromaticity Bins: 1931 CIE Curve



The following tables describe the four chromaticity points that bound each chromaticity bin. Chromaticity bins are grouped together based on the color temperature.

6500K Chromaticity Bins		
Bin Code (WW)	CIEx	CIEy
DG	0.307	0.311
	0.322	0.326
	0.323	0.316
	0.309	0.302
F3*	0.305	0.321
	0.313	0.329
	0.315	0.319
	0.307	0.311
F4*	0.303	0.330
	0.312	0.339
	0.313	0.329
	0.305	0.321
G3*	0.313	0.329
	0.321	0.337
	0.322	0.326
	0.315	0.319
G4*	0.312	0.339
	0.321	0.348
	0.321	0.337
	0.313	0.329
EF	0.302	0.335
	0.320	0.354
	0.321	0.348
	0.303	0.330
DE	0.283	0.304
	0.303	0.330
	0.307	0.311
	0.289	0.293
DF	0.289	0.293
	0.307	0.311
	0.309	0.302
	0.293	0.285

5700K Chromaticity Bins		
Bin Code (WW)	CIEx	CIEy
DJ	0.322	0.324
	0.337	0.337
	0.336	0.326
	0.323	0.314
H3*	0.321	0.335
	0.329	0.342
	0.329	0.331
	0.322	0.324
H4*	0.321	0.346
	0.329	0.354
	0.329	0.342
	0.321	0.335
J3*	0.329	0.342
	0.337	0.349
	0.337	0.337
	0.330	0.331
J4*	0.329	0.354
	0.338	0.362
	0.337	0.349
	0.329	0.342
EH	0.320	0.352
	0.338	0.368
	0.338	0.362
	0.321	0.346

*Sub-bins within ANSI defined quadrangles per ANSI C78.377-2008

5000K Chromaticity Bins		
Bin Code (WW)	CIE _x	CIE _y
EK	0.338	0.368
	0.356	0.384
	0.355	0.376
	0.338	0.362
K3*	0.337	0.349
	0.345	0.355
	0.345	0.343
	0.337	0.337
K4*	0.338	0.362
	0.347	0.369
	0.345	0.355
	0.337	0.349
M3*	0.345	0.355
	0.353	0.349
	0.352	0.372
	0.344	0.343
M4*	0.346	0.369
	0.355	0.376
	0.353	0.362
	0.345	0.355
DM	0.337	0.337
	0.352	0.349
	0.350	0.337
	0.336	0.326

4500K Chromaticity Bins		
Bin Code (WW)	CIE _x	CIE _y
EN	0.356	0.384
	0.376	0.396
	0.374	0.387
	0.355	0.374
N3*	0.353	0.360
	0.361	0.366
	0.359	0.352
	0.351	0.347
N4*	0.355	0.374
	0.364	0.381
	0.361	0.366
	0.353	0.360
P3*	0.361	0.366
	0.370	0.373
	0.367	0.358
	0.359	0.352
P4*	0.364	0.381
	0.374	0.387
	0.370	0.373
	0.361	0.366
DP	0.351	0.347
	0.367	0.358
	0.364	0.346
	0.350	0.335

*Sub-bins within ANSI defined quadrangles per ANSI C78.377-2008

4000K Chromaticity Bins		
Bin Code (WW)	CIE _x	CIE _y
EQ	0.376	0.396
	0.404	0.414
	0.401	0.404
	0.374	0.387
Q3*	0.370	0.373
	0.382	0.380
	0.378	0.365
	0.367	0.358
Q4*	0.374	0.387
	0.387	0.396
	0.382	0.380
	0.370	0.373
R3*	0.382	0.380
	0.395	0.388
	0.390	0.372
	0.378	0.365
R4*	0.387	0.396
	0.401	0.404
	0.395	0.388
	0.382	0.380
DR	0.367	0.358
	0.390	0.372
	0.386	0.359
	0.364	0.346

*Sub-bins within ANSI defined quadrangles per ANSI C78.377-2008

Product Shipping & Labeling Information

All SST-50 products are packaged and labeled with their respective bin as outlined in the tables from pages 3 to 7. When shipped, each package will only contain one bin. The part number designation is as follows:

SST — 50 — WNNX — F21 — FF — WW

Product Family	Chip Area	Color	Package Configuration	Flux Bin	Chromaticity Bin
Surface Mount (Lens)	5.0 mm ²	CCT & CRI See Note 1 below	Internal Code	See page 3 for bins	See page 4-7 for bins

Note 1: WNNX nomenclature corresponds to the following:

W = White

NN = color temperature, where:

65 corresponds to 6500K

X = color rendering index, where:

S (standard) corresponds to a typical CRI of 70

Note 2: Some flux and chromaticity bins may have limited availability. Application specific bin kits, consisting of multiple bins, may be available. For ordering information, please refer to page 15 and reference PDS-001848: SST-50 Binning & Labeling document.

Example:

The part number SST-50-W65S-F21-J3-G4 refers to a 6500K standard CRI white, SST-50 emitter, with a flux range from 475 to 500 lumens and a chromaticity value within the box defined by the four points (0.313, 0.338), (0.321, 0.348), (0.322, 0.336), (0.312, 0.328).

Electrical Characteristics¹

Optical and Electrical Characteristics (T_j = 25 °C)

Drive Condition ²		1.75 A	
Parameter	Symbol	Test Current	Unit
Current Density	j	0.35	A/mm ²
Forward Voltage	V _{F,min}	2.5	V
	V _{F,typ}	3.2	V
	V _{F,max}	3.9	V

Common Characteristics

Parameter	Symbol	Values	Unit
Viewing Angle	2 θ _{1/2}	100	
Emitting Area	A	5.0	mm ²
Emitting Area Dimensions		2.25 x 2.25	mm×mm
Forward Voltage Temperature Coefficient ⁴		-4.4	mV/°C

Absolute Maximum Ratings

Parameter	Symbol	Values	Unit
Maximum Current ⁵		5.0	A
Maximum Reverse Current		N/A	
Maximum Junction Temperature ⁶	T _{j,max}	150	°C
Storage Temperature Range		-40/+100	°C

Note 1: Listed drive conditions are typical for common applications. SST-50 White devices can be driven at currents ranging from <1A to 5A and at duty cycles ranging from <1% to 100%. Drive current and duty cycle should be adjusted as necessary to maintain the junction temperature desired to meet application lifetime requirements.

Note 2: Unless otherwise noted, values listed are typical.

Note 3: Forward voltage temperature coefficient at 1.75A. Contact Luminus for value at other drive conditions.

Note 4: SST-50 devices are designed for operation to an absolute maximum forward drive current 5A. Product lifetime data is specified at recommended forward drive currents. Sustained operation at absolute maximum currents will result in a reduction of device lifetime compared to recommended forward drive currents. Actual device lifetimes will also depend on junction temperature. Refer to APN-001521: Reliability Application Note for SST-50-W for further information. In pulsed operation, rise time from 10-90% of forward current should be larger than 0.5 microseconds.

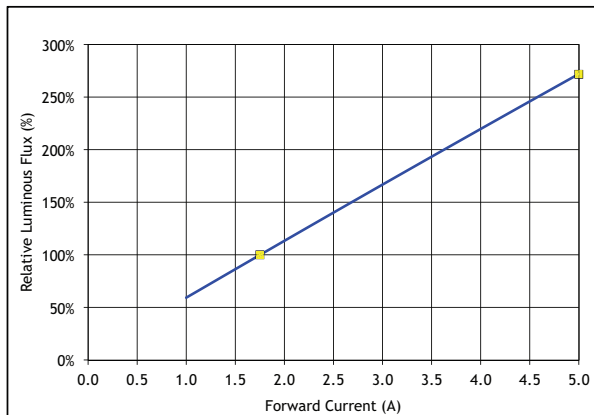
Note 5: Lifetime dependent on LED junction temperature. Thermal calculations based on input power and thermal management system should be performed to ensure T_j is maintained below T_{j,max} rating or life will be reduced. Refer to APN-001521 for further information.

Note 6: CIE measurement uncertainty for white devices is estimated to be +/- 0.01.

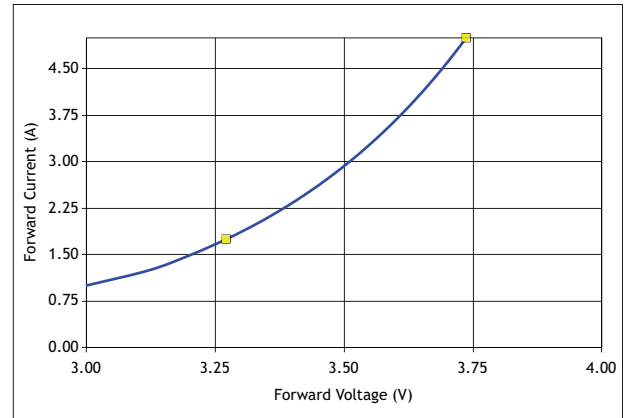
Note 7: Special design considerations must be observed for operation under 1A. Please contact Luminus for further information.

Note 8: Caution must be taken not to stare at the light emitted from these LEDs. Under special circumstances, the high intensity could damage the eye.

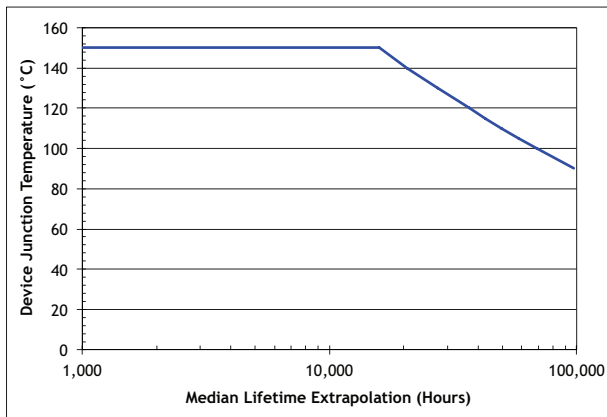
Relative Output Flux vs. Forward Current¹



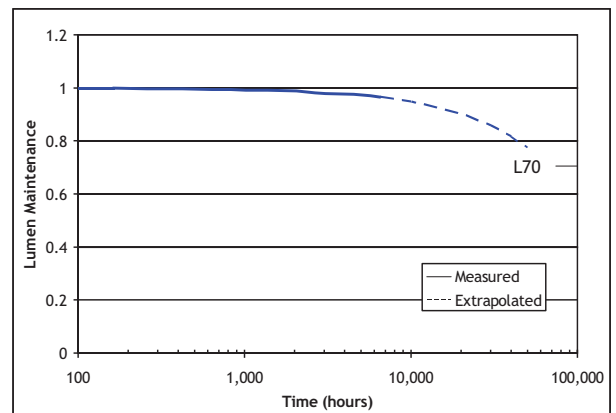
Forward Current vs. Forward Voltage



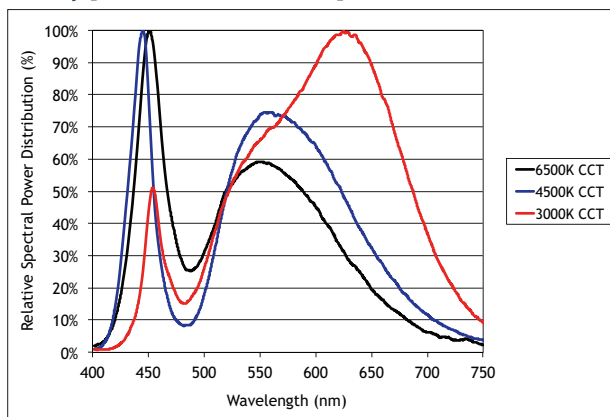
Mean Lifetime²



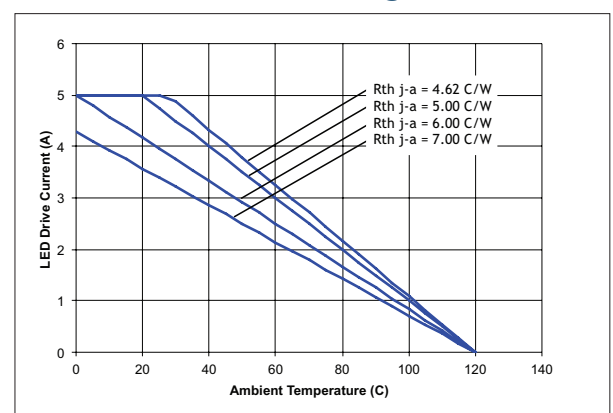
Lumen Maintenance vs. Time³



Typical Relative Spectral Power⁴



Current Derating Curve



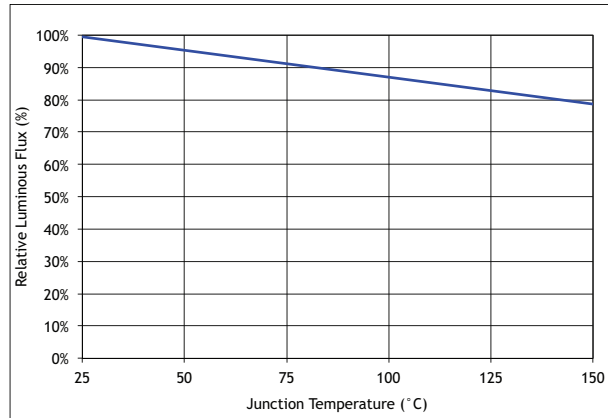
Note 1: Yellow squares indicate typical operating conditions.

Note 2: Mean expected lifetime in dependence of junction temperature at 0.35 A/mm² in continuous operation. Lifetime defined as time to 70% of initial intensity. Based on lifetime test data of uncoated GaN devices at this time. Data can be used to model failure rate over typical product lifetime (contact Luminus for lifetime reliability test data for 1A/mm² condition).

Note 3: Lumen maintenance in dependence of time at 0.35 A/mm² in continuous operation with junction temperatures of 100 °C.

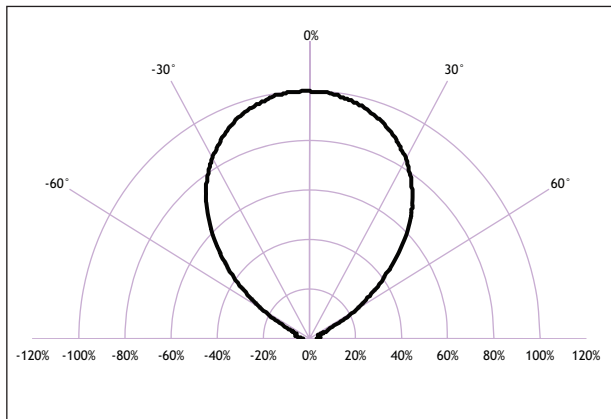
Note 4: Typical spectrum at current density of 0.35 A/mm² in continuous operation.

Relative Output Flux vs. Junction Temperature

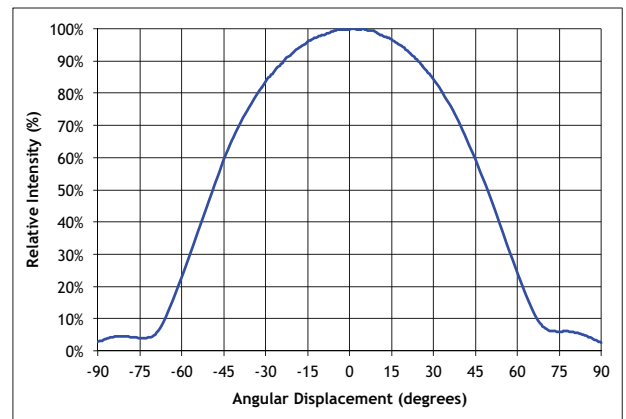


Typical Radiation Pattern

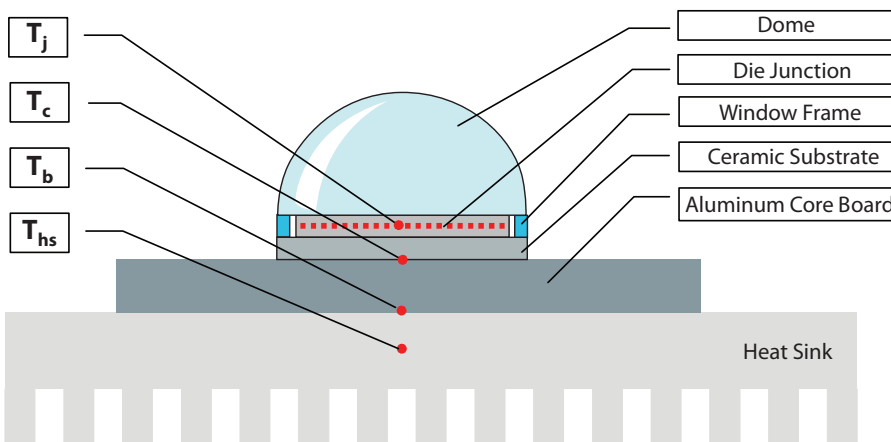
Typical Polar Radiation Pattern for White



Typical Angular Radiation Pattern for White



Thermal Resistance



Typical Thermal Resistance, junction to case

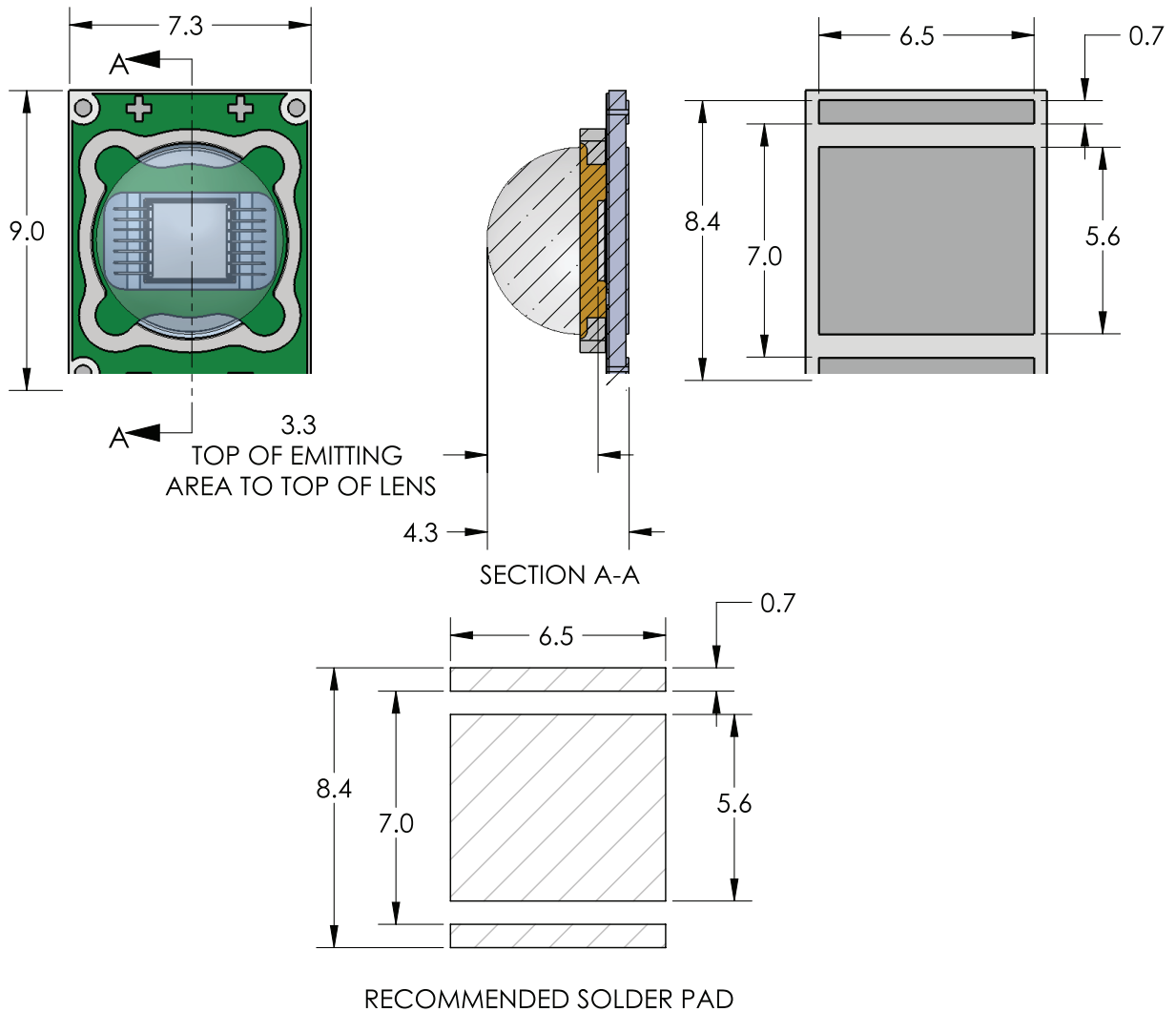
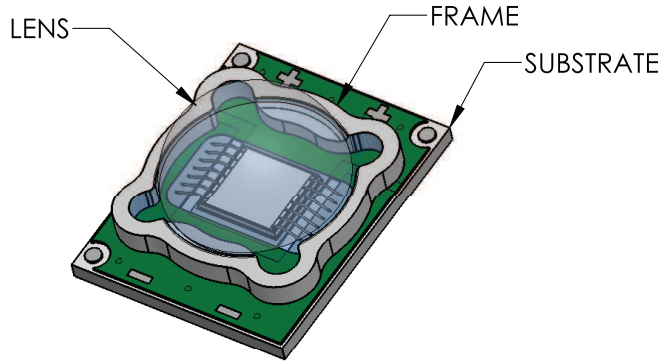
R_{j-c}^1	2.45 °C/W
R_{j-b}^1	4.28 °C/W
R_{j-hs}^2	4.39 °C/W

Note 1: Thermal resistance values are based on FEA model results correlated to measured $R_{\theta j-hs}$ data.

Note 2: Thermal resistance is measured using a SAC305 solder, a Bergquist Al-clad MCPCB, and eGraf 1205 thermal interface material.

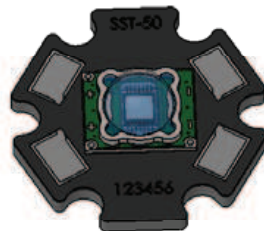
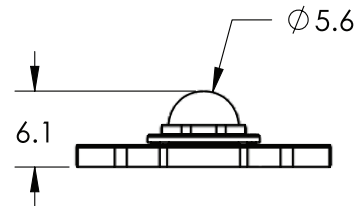
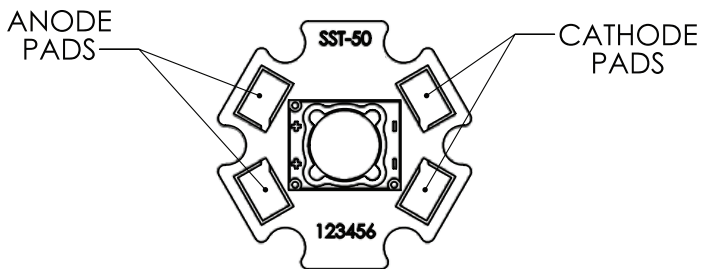
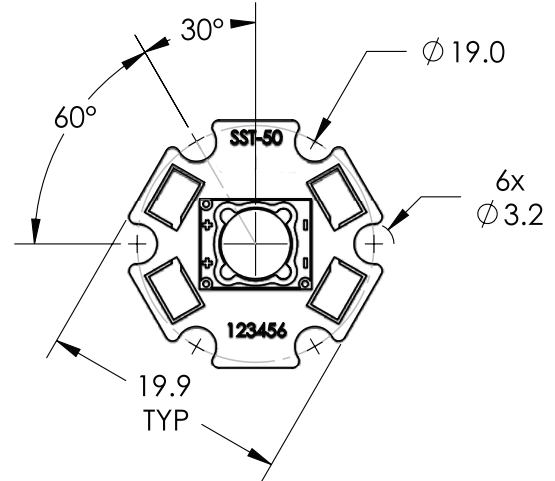
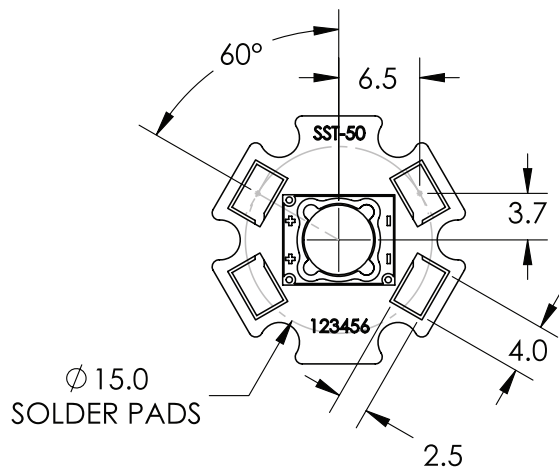
Mechanical Dimensions – SST-50 Emitter

DIMENSIONS IN MILLIMETERS



For detailed drawing please refer to DWG-001358 document

Mechanical Dimensions – SST-50 Star Board



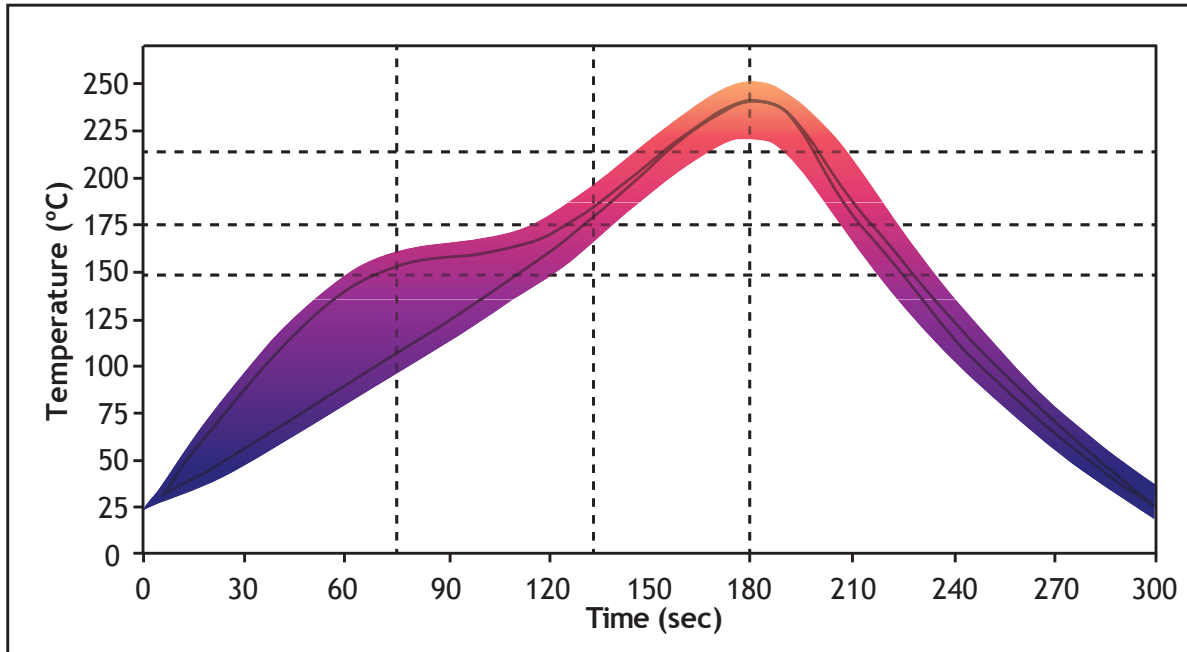
Note 1: Recommended mounting screw: M3 or #4

Note 2: All dimensions in millimeters

Note 3: anode pads on board are interconnected. All cathode pads on board are interconnected

Solder Profile

SAC 305 Reflow Profile Window For Low Density Boards



Lead free solder guideline for low density boards

Solder Profile Stage	Lead-Free Solder	Lead-based Solder
Profile length, Ambient to Peak	2.75 - 3.5 minutes	2.75 - 3.5 minutes
Time Maintained Above: Temperature	217 °C	217 °C
Time Maintained Above: Time	30 - 60 seconds	30 - 60 seconds
Cooldown Rate	≤4° C/sec	≤4° C/sec
Cooldown Duration	45 ± 15 sec	45 ± 15 sec

Note 1: Temperatures are taken and monitored at the component copper layer.

Note 2: Optimum profile may differ due to oven type, circuit board or assembly layout.

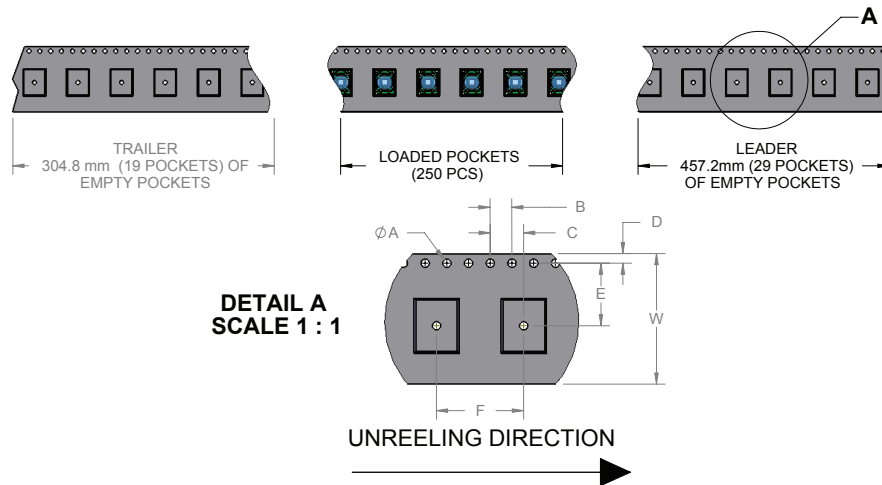
Note 3: Recommended lead free, no-clean solder: AIM NC254-SAC305.

Note 4: Refer to APN-001473 soldering and handling application note for additional solder profiles and details.

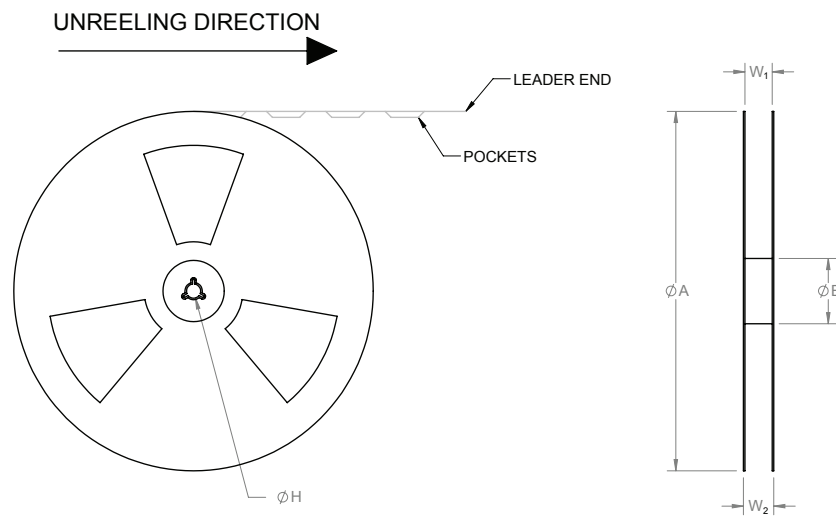
Note 5: MSL- 2A for SST parts only. The SSR product has no moisture sensitivity rating.

Tape and Reel Drawing of SST-50

DIMENSIONS ARE IN mm. (INCH)



TAPE DIMENSIONS						
W	ϕA	B	C	D	E	F
24.0 (.945)	1.5 (.059)	3.9 (.157)	6.1 (.241)	1.7 (.069)	11.5 (.453)	16.0 (.630)



REEL DIMENSIONS				
ϕA	W_1	W_2	ϕB	ϕH
$\phi 330.2$ (13.0)	25 (.984)	27.8 (1.094)	60.0 (2.362)	$\phi 13.0$ (.512)

Ordering Information

Ordering Part Number ^{1,2}	Color	Description
SST-50-WDLS-F21/T21-GG150	6500K White 5700K White	White Big Chip LED™ SST-50 surface mount device consisting of a 5mm ² LED on a ceramic substrate, F21- tray pack, T21- tape & reel pack
SST-50-WCLS-F21/T21-GG450	4500K White 4000K White	
SSR-50-WDLS-R21-GG150	6500K White 5700K White	SSR-50 evaluation module consisting of a SST-50 surface mount device mounted on an aluminum star board
SSR-50-WCLS-R21-GG450	4500K White 4000K White	

Note 1: GG150 - denotes a bin kit comprising of all flux and chromaticity bins at the 6500K and 5700K color points

GG450 - denotes a bin kit comprising of all flux and chromaticity bins at the 4500K and 4000K color points

Note 2: For ordering information on all available bin kits, please see PDS-001848: SST-50 Binning & Labeling document

The products, their specifications and other information appearing in this document are subject to change by Luminus Devices without notice. Luminus Devices assumes no liability for errors that may appear in this document, and no liability otherwise arising from the application or use of the product or information contained herein. None of the information provided herein should be considered to be a representation of the fitness or suitability of the product for any particular application or as any other form of warranty. Luminus Devices' product warranties are limited to only such warranties as accompany a purchase contract or purchase order for such products. Nothing herein is to be construed as constituting an additional warranty. No information contained in this publication may be considered as a waiver by Luminus Devices of any intellectual property rights that Luminus Devices may have in such information. Big Chip LEDs™ is a registered trademark of Luminus Devices, Inc., all rights reserved.

This product is protected by U.S. Patents 6,831,302; 7,074,631; 7,083,993; 7,084,434; 7,098,589; 7,105,861; 7,138,666; 7,166,870; 7,166,871; 7,170,100; 7,196,354; 7,211,831; 7,262,550; 7,274,043; 7,301,271; 7,341,880; 7,344,903; 7,345,416; 7,348,603; 7,388,233; 7,391,059 Patents Pending in the U.S. and other countries.